

Contents

Contents of Volume 1 xlvii

V: THE CURRENT-CARRYING MIXED STATE

Chapter 20. The Current-Carrying Mixed State at Low and High Fields

20.1	Introduction	3
20.1.1	Early Models of the Current-Carrying Mixed State— Heterogenous Superconductors	3
20.1.2	Scope of the Following Group of Chapters	4
20.2	Flux-Pinning Theory	5
20.3	Experimental Aspects of Flux Pinning	7
20.4	Nonorthogonality of Applied Field and Transport Current	8
20.5	Critical State Models of the Current-Carrying Mixed State	8
20.6	The Low-Field “Critical State” and High-Field “Pinned Trans- port Current” Regimes	11
20.6.1	The Intermediate-Field Regime	11
20.6.2	The High-Field Paramagnetic Mixed State	12
20.6.3	Discussion of the Ti–Nb M–H Diagram	13
	(a) Low and Intermediate Fields	13
	(b) High Fields	14
20.6.4	Field Gradients and Boundary Values in Low and High Fields	14

Chapter 21. Flux Pinning and Critical Current Density

PART 1. FLUX-PINNING THEORY

21.1 Principles of Flux Pinning	17
21.1.1 Introduction to Pinning Theory	17
21.1.2 Introduction to the Flux-Pinning Literature—Plan of Part 1 of this Chapter	20
(a) The Elementary Pinning Force, f_p	20
(b) The Bulk Pinning Force Density, F_p —Pinning Force Summation	20
(c) Plan of Part 1 of this Chapter	22
21.2 The Elementary Pinning Force, f_p	22
21.2.1 Pinning by Voids	22
21.2.2 Pinning by Normal Precipitates	23
(a) Early Analyses of Precipitate Pinning	23
(b) Flux Pinning by Small, or Thin, Precipitates	24
(i) Proximity-Effect Theory	24
(ii) Application of the Theory to Precipitated Alloys	25
21.2.3 Pinning by Magnetic Precipitates	26
(a) Strongly Paramagnetic Precipitates	26
(b) Ferromagnetic Precipitates	26
21.2.4 Pinning by Dislocation-Cell Walls	27
(a) Classical Theory	27
(b) Recent Advances	28
21.3 Bulk Pinning-Force Density—I: The Direct Summation Model	29
21.3.1 Direct Summation of the Elementary Cell-Wall Pinning Function	29
(a) Introduction of Flux-Lattice Plasticity	29
(b) Form of the Pinning Function	29
(c) Dislocation Cell Diameter	30
(d) The J_c versus H_a Relationship	30
21.3.2 Reduced Form of the Pinning Function—Scaling	31
21.3.3 The Cell-Wall $\Delta\kappa$ Factor—Influence of Electronic Mean- Free-Path	33
21.3.4 The Characteristic Force-Integration Distance, Δ_p	34
21.3.5 Further Development of Bulk Pinning Functions	34
21.3.6 The Pinning-Force Maximum as it Relates to the Concept of Matching	35
21.4 Bulk Pinning-Force Density—II: The Elastic-Lattice Summa- tion Model of Fietz and Webb	35
21.4.1 The Summation Model	35

21.4.2 The Pinning-Force Threshold in the Context of the Fietz-Webb Model 36

21.5 Elastic Stiffness Moduli of the Flux Lattice 37

21.5.1 Development of the Local and Nonlocal Moduli 37

21.5.2 General Discussion of the Field Dependence of the Shear Modulus 38

21.6 Bulk Pinning-Force Density—III: The Elastic Summation Model of Labusch 39

21.6.1 Development of the Labusch Model 39

21.6.2 High-Field Approximation to the Labusch Bulk Pinning Force 40

21.6.3 The Pinning Force Threshold in General 41

(a) Development of the Threshold Concept 41

(b) Discussion of the Threshold Problem 42

21.7 Discussion of the Elastic-Lattice Pinning Functions 43

21.7.1 The Pinning Force Maxima 43

21.7.2 Derived Expressions for the Critical Current Density 44

21.7.3 Properties of the Pinning Function, $H_{c2}^m f(h)$ 44

21.8 Extension of Elastic-Lattice Flux-Pinning Theory to the Paramagnetic Mixed State 46

21.9 The Present Status of Flux-Pinning Theory 47

21.9.1 Introduction 47

21.9.2 The Direct-Summation and Labusch Extremes 48

(a) The Direct-Summation Model 49

(b) The Labusch Model 49

21.9.3 Introduction of the Periodic Elementary Interaction Potential 50

(a) Periodic Potentials and Labusch's Approximation 50

(b) Campbell's Model 50

21.9.4 Recent Developments and Advances 51

21.10 Scaling Laws 52

21.10.1 Simple Scaling 52

(a) Scaling in Ti-Nb(95 at.%), H_a Perpendicular to the Rolling Plane 53

(b) Scaling in Ti-Nb(83 at.%), H_a Parallel to the Rolling Plane 53

21.10.2 Breakdown of Simple Scaling 53

(a) Influence of the Elementary Pinning-Force Threshold 53

(b) Influence of Pauli Paramagnetism 53

21.10.3 Scaling in the Paramagnetic Mixed State 54

(a) General Description 54

(b) A Case Study of Ti-V(36 at.%)	54
21.11 Matching	56
21.11.1 Matching in General	56
21.11.2 Matching in Ti-Nb Alloys	57
21.12 The Peak Effect	59
21.12.1 Comparisons Between the Flux Lattice and the Crystal Lattice	59
21.12.2 Occurrence and Properties of the Peak Effect	59
21.12.3 Experimental Studies of the Peak Effect	61
21.12.4 Mechanisms of the Peak Effect	64
(a) Results of Early Investigations	64
(b) Presently Accepted Model	65

PART 2. EXPERIMENTAL FLUX PINNING

21.13 Flux-Pinning Precipitates	70
21.13.1 Precipitation from Low-Concentration Ti-Nb(<30 at.%) Alloys	70
21.13.2 Precipitation from Intermediate-Concentration Ti-Nb(30-40 at.%) Alloys	71
(a) General Discussion: Difficulties in Measurement and Interpretation	71
(b) Precipitation from Heavily Cold-Worked Ti-Nb Alloys: Background	73
(c) Precipitation from Heavily Cold-Worked Ti-Nb Alloys: Recent Results	74
21.13.3 Flux Pinning in High-Concentration Ti-Nb(>40 at.%) Alloys	79
21.13.4 Flux-Pinning Precipitation in Ti-Zr-Nb Alloys	80
21.13.5 Precipitation Induced by Third-Element Additions to Ti-Nb and Ti-Nb-Base Alloys	81
(a) α -Phase Precipitation from $\omega + \beta$	81
(b) α -Phase Precipitation from $\beta' + \beta$	81
21.13.6 Flux Pinning Associated with Interstitial-Element Additions to Ti-Nb and Ti-Nb-Base Alloys	82
(a) The Influence of Boron	82
(b) The Influence of Carbon	82
(c) The Influence of Nitrogen	82
(d) The Influence of Oxygen	83
(e) Synopsis of Interstitial Effects	84
21.14 Flux Pinning by Subbands	86
21.15 Flux Pinning by Subbands and Precipitates	90
21.15.1 Introduction	90

21.15.2 The Relative Importances of Subband Size and Precipitation 91

 (a) The “Subband *versus* Precipitation” Experiments of Arndt and Ebeling 91

 (b) The “Subband *versus* Precipitation” Experiments of West and Larbalestier 94

21.15.3 Quantitative Relationships Between J_c , the Subband Size, and the Sizes and Shapes of the Precipitates 96

21.15.4 Precipitate Size, Shape, and Placement with Respect to Subband Structure 98

 (a) Early Studies of Flux-Pinning Precipitates in Deformed Ti-Nb Alloys 98

 (b) Recent Studies of Flux-Pinning Precipitates in Deformed Ti-Nb Alloys 98

 (c) Recent Studies of Flux-Pinning Precipitates in Deformed Ti-Zr-Nb-Ta Foil and Filamentary Specimens 99

21.16 Directional Anisotropy in the Influence of an Applied Field on the Critical Current Density 100

 21.16.1 Transverse Anisotropy 100

 21.16.2 Longitudinal Anisotropies 100

 (a) Pinning-Force Anisotropy 100

 (b) Electromagnetic Anisotropy 100

21.17 Longitudinal Electromagnetic Anisotropy 104

21.18 Longitudinal Pinning-Force Anisotropy 105

 21.18.1 Isotropic Distribution of Pinning Centers 105

 21.18.2 Anisotropic Distribution of Pinning Centers 107

 21.18.3 Summary 109

PART 3. CRITICAL CURRENT DENSITY

21.19 Critical Current Optimization 109

 21.19.1 Introduction 109

 21.19.2 Intermediate Heat Treatment 110

 21.19.3 Final Cold Deformation 111

 21.19.4 Precipitate Redistribution by Flattening 113

21.20 Recent Advances in the Critical Current Density of Titanium-Niobium and Prospects for Its Improvement 115

 21.20.1 Introduction 115

 21.20.2 Total Area Reduction *versus* Final Cold Work 117

 21.20.3 Critical Current Densities of Ti-Nb Alloy Superconductors—Some Experimental Results 118

 21.20.4 Thermomechanical-Process Optimization 119

21.20.5	Fundamental Approaches to J_c Improvement	120
(a)	Influence of Temperature on the High-Field J_c	121
(b)	Improvements to High-Field J_c through Alloy Design	122
21.21	Critical Current Densities of Ti-Nb-Base Alloy Superconductors—Some Experimental Results	123
21.21.1	Simple-Metal and interstitial-Element Additions to Ti-Nb	123
21.21.2	Substitutes for Titanium in Ti-Nb Alloys	123
(a)	Critical Current Densities of Ti-Zr-Nb Alloys	123
(i)	Superconducting Alloy Development	124
(ii)	Present Status of Ti-Zr-Nb Superconductivity	124
(b)	Critical Current Densities of Ti-Hf-Nb Alloys	126
21.21.3	Substitutes for Niobium in Ti-Nb Alloys	128
(a)	Critical Current Densities of Ti-Nb-V Alloys	128
(b)	Critical Current Densities of Ti-Nb-Ta Alloys	128
21.21.4	Substitutes for Titanium and Niobium in Ti-Nb Alloys	130
(a)	Critical Current Densities of Ti-Zr-Hf-Nb Alloys	130
(b)	Critical Current Densities of Ti-Zr-Nb-Ta Alloys	130
21.22	Compositional Inhomogeneity in Ti-Nb-Base Alloys	132

Chapter 22. Current Transport in a Longitudinal Applied Magnetic Field

22.1	Direct Current Transport in a Steady Longitudinal Applied Field	133
22.2	Elementary Theory for Ideal (Reversible, Unpinned) Type-II Superconductors	134
22.2.1	Conditions of the Model	134
22.2.2	The Field Distribution	134
22.2.3	Relationship Between Average Magnetization and the Critical Current	135
22.2.4	Physical Interpretation	136
22.2.5	Example of the Force-Free Model	137
22.3	Pinning-Force Theory of Critical Current in a Longitudinal Applied Field	138
22.3.1	Establishment of the Basic Equations	138
22.3.2	History Effects in Longitudinal-Field Magnetization	141
22.3.3	Intrinsic Critical Current Density Anisotropy	142

22.4 Alternating Current in a Steady Longitudinal Applied Field 142

22.4.1 AC Losses 142

22.4.2 The Induced Alternating Axial Magnetization 145

22.4.3 Features of the Critical-State Description 147

(a) Axial Current Density, J_z 149

(b) Azimuthal Induction, B_θ 149

(c) Axial Induction, B_z 149

(c) Azimuthal Current Density, J_θ 149

22.5 Surface Sheaths and Surface Barriers 149

22.5.1 The Surface Sheath 149

22.5.2 Surface Sheath and Surface Barrier 150

22.5.3 The Surface Barrier 151

22.6 Experimental Studies of the Surface Barrier Supercurrent 152

22.6.1 General Discussion 152

22.6.2 Evaluation of the Surface Supercurrent from the Results of Longitudinal AC Hysteresis Measurements 153

22.7 Synopsis of Longitudinal Effects 154

Chapter 23. Flux in Motion under the Influence of a Transport Current

23.1 Beyond the Critical State 155

23.2 Critical Current Density Criteria 157

23.2.1 General Considerations 157

23.2.2 The Choice of Transition Criterion 158

(a) The Superconducting/Normal Transition 158

(b) The Minimum Detectable Voltage 159

(c) The Voltage Gradient or Electric Field 159

(d) The Minimum Resistivity 159

(e) The Power Density 159

23.2.3 The Self-Field of the Transport Current 159

23.2.4 Positioning of the Voltage Taps: The Current-Transfer Effect 160

23.3 Current Transfer in Superconducting Composites 160

23.3.1 Symptoms of Current Transfer 160

23.3.2 Current Transfer in Filamentary Cu-Matrix Composites 162

23.3.3 Current Transfer in Filamentary Cu-Ni-Matrix Composites 163

23.4 Critical Current Density Measurement 163

23.4.1 Development of Standard Procedures 163

23.4.2	Standard Test Method for Small (Less than 600 A) Composite Conductors	165
23.4.3	Measurement, with Specification, of the Critical Current of a Large Conductor (The CBA Conductor)	166
23.5	Equipment for Critical Current Measurement	167
23.5.1	Sample Mounting	167
23.5.2	Electronics	169
23.5.3	Contact-Free Methods of Critical Current Determination	169
23.6	Transport-Current-Induced Flux Creep	170
23.7	Transport-Current-Induced Flux Flow	171
23.8	Flow Resistivity and Viscosity in Terms of the Parameters of the Mixed State	172
23.8.1	The Flux-Flow Resistivity, ρ_f	172
23.8.2	The Viscosity Coefficient, η	174
23.9	Flux-Flow Determination of the Upper Critical Field	174
23.9.1	Flux-Flow Determination of H_{c20}^* in Ti-V Alloys	174
23.9.2	Flux-Flow Determination of H_{c20}^* in Ti-Nb Alloys	175
23.9.3	Flux-Flow Determination of $H_{c2}(t)$	176
23.10	Synopsis—The Occurrence and Mechanisms of Flux Flow	177
23.11	The Superconductive Hall Effect	177
23.11.1	Occurrence of the Hall Effect	177
23.11.2	Experimental Studies of the Hall Effect	179
23.12	Thermomagnetic Properties of the Mixed State	180
23.12.1	The Peltier and Ettingshausen Effects	182
23.12.2	The Nernst Effect	184
23.13	Flux Jumping under the Influence of a Transport Current	185
23.13.1	The Complete Flux Jump	185
23.13.2	Flux-Jump Limitation	187
23.14	Flux Motion as a Dissipative Process—Heat Transfer from a Current-Carrying Superconductor to the Liquid Helium Bath	188
23.14.1	Bare Superconductor	188
23.14.2	Influence of Copper Stabilization	191
23.14.3	Further Studies of Flux-Jump Stability and Cryostability	192

Chapter 24. Small-Coil Testing

24.1	Role of the Small-Coil Test	193
24.2	Testing Procedures	194

24.3 Experimental Details 194

24.4 Properties Investigated in Small-Coil Testing 198

 24.4.1 Very Early Developmental Studies of Composite Conduc-
 tors and Their Testing in Small Coils 198

 24.4.2 Materials Studies 199

 24.4.3 Wire Selection 200

 (a) Conventional Cu/Ti-Nb Composites 201

 (b) Intermediate-Resistivity-Matrix Ti-Nb
 Composites 201

24.5 Degradation, Training, and Potting 202

 (a) Untwisted-Wire Coils 204

 (b) Twisted-Wire Coils 204

24.6 Cryogenics 205

24.7 Stability in Conductor and Magnet Performance 206

24.8 Reduced-Temperature High-Field Performances of Small Test
 Coils: Some Recent Studies 207

**VI. DESIGN AND FABRICATION OF COMPOSITE
SUPERCONDUCTORS**

Chapter 25. Stability

25.1 Stability and Stabilization 211

25.2 Flux-Jump Stabilization 213

25.3 Cryogenic Stabilization 214

25.4 Magnitudes of Commonly Encountered Disturbances 214

 25.4.1 Flux-Jump Instability 214

 25.4.2 Mechanical Instabilities 215

 (a) Tensile Failure of the Potting Resin 215

 (b) Shear Failure of the Bond Between an Epoxy
 Impregnant and the Conductor 215

 (c) Microyielding of the Entire Composite 215

 (d) Serrated Yielding 215

 (e) Friction Between the Metallic and Insulating Sur-
 faces 215

25.5 Organization of the Chapter 218

PART 1. FLUX-JUMP STABILITY

25.6 Adiabatic Stabilization of the Bare Monofilament 219

25.7 Filamentary Stabilization 220

25.8 Enthalpy Stabilization 221

25.9	Special Design Techniques	223
25.9.1	Critical Current Control	223
25.9.2	Conductor Design	223
25.10	The Multifilamentary Composite	224
25.11	External Field Instability—Twist	225
25.11.1	Twist Pitch	226
25.11.2	Limitation to Twist Pitch	229
25.12	The Phenomenology of Adiabatic Self-Field Flux-Jump Instability	229
25.12.1	Self-Field-Induced Flux Jumping	229
25.12.2	Limiting Composite Diameter for Adiabatic Self-Field Stability	231
25.12.3	The Role of Transposition in Self-Field Stability	232
25.12.4	Other Factors that Influence Self-Field Flux-Jump Sta- bility	232
	(a) The Effect of an External Field	232
	(b) Dynamic Stabilization	232
	(c) Reduced-Current Stabilization	232
	(d) Reduced-Current Recovery	232
	(e) Current Redistribution under Forced Current Sharing	233
	(f) The Spiral-Field Effect	233
25.13	The Mechanism of Adiabatic Self-Field Flux-Jump Instability	234
25.13.1	The Self-Field Effect	234
25.13.2	Self-Field Instability of the Fully Saturated Untransposed Composite	236
25.13.3	Reduced Self-Field Instabilities of Twisted and Current- Degraded Composites	236
	(a) The Influence of Twist	237
	(b) The Influence of Transport Current Reduction	238
25.14	The Influence of an Externally Applied Field on the Adiabatic Self-Field Flux-Jump Stability	239
25.15	Self-Field Stability of Strands and Cable in the Presence of an External Field	241
25.15.1	Stability of the Strand	241
25.15.2	Stability of Cable	242
25.16	Influence on Flux-Jump Instability of Departures from Adiabaticity	242
25.17	Dynamic Stability	243
25.17.1	Electromagnetic Diffusion	243
25.17.2	Influence of Stabilizer Resistivity	244
25.18	Analysis of Dynamic Stability	244

25.18.1	The Basic Equation	244
(a)	Adiabatic Stability	245
(b)	Dynamic Stability	245
25.18.2	The Stabilizer-to-Superconductor Ratio, R_s	247
(a)	Cylindrical Conductors	247
(b)	Flat Conductors	248
25.19	Adiabatic and Dynamic Stabilization: A Comparison	248
(a)	Adiabatic Stabilization	248
(b)	Dynamic Stabilization	248
(c)	Ratio of the Maximum Stable Filament Diameters	249
25.20	Dynamic Self-Field Flux-Jump Instability	249
25.20.1	Introduction	249
25.20.2	The Theory of Duchateau and Turck	249
25.20.3	Results of the Dynamic Self-Field Analysis	252

PART 2. CRYOSTABILITY

25.21	Principles of Cryostabilization	252
25.21.1	Background	252
25.21.2	Components of the Theory	253
(a)	The “Disturbance,” $\dot{G}_d$	253
(b)	The “Heat Generation,” $\dot{G}$	254
(c)	The “Cooling,” $\dot{Q}$	254
(d)	Conduction of Heat	255
(e)	Storage of Heat	255
(f)	Dimensionality	255
25.21.3	Cryostability Theory with Case Studies: Recommended Further Reading	255
25.21.4	Presentation of Cryostability Theory	256
(a)	First Approach	257
(b)	Second Approach	257
25.21.5	Organization of the Remaining Parts of this Chapter	258
25.22	Current Sharing and Transfer	259
25.22.1	Interrelationships Between Current, Voltage, Field, and Temperature	259
(a)	Current as a Control Variable	260
(b)	Temperature as a Control Variable	260
25.22.2	The Heat Generation	262
25.23	Conductor Performance Levels	263
25.24	Full Cryostability—Stekly’s Criterion	265
25.24.1	The Threshold of Zero-Dimensional Stability	267

25.24.2	General Zero-Dimensional Cryostability	268
25.25	Cryostability under Current Control	269
25.25.1	Form of the Current-Voltage Characteristic in the Current-Sharing Regime	270
25.25.2	The Current-Sharing Function, $f(t)$	271
25.26	Cryostability at Constant Current under Temperature Control	271
25.27	The Complete Stekly Stability Criterion	273
25.28	Design of Cryostable Conductors	274
25.28.1	Conductor Diameter and the Cu/SC Ratio	274
25.28.2	Choice of Filament Diameter	276
25.29	Influence of the Transition from Nucleate to Film Boiling on the Current-Voltage Characteristic	277
25.30	Full Cryostabilization—Cold-End Recovery	278
25.30.1	The Introduction of Longitudinal Heat Flow (Conduction)	278
25.30.2	Analysis of the Cold-End Heat-Balance Equation	278
25.30.3	Analysis of Cold-End Recovery under Linear Cooling	279
25.30.4	The Equal-Area Theorem under Linear Cooling	281
25.31	Cold-End Recovery under Generalized Nonlinear Cooling	282
25.31.1	The General Theorem of Maddock, James, and Norris	282
25.31.2	Case Study—Cold End Recovery in a Model MFTF Conductor	284
25.32	Limited Cryostabilization—The MPZ-Modified Cold-End Criterion	285
25.32.1	Principles of Limited Stability	285
25.32.2	MPZ Formation Energy and Conductor Stability	287
25.32.3	MPZ Formation Energy, Conductor Stability, and Cu/SC Ratio	290
25.33	Resistive Zones in One Dimension	291
25.33.1	Equilibrium States of the Uniform One-Dimensional Conductor	291
25.33.2	Localized Permanent-Fault Stability of the One-Dimensional Conductor	293
25.34	Properties of “Uncooled” MPZs	294
25.34.1	The Origin and Generalization of MPZ Theory	294
25.34.2	Establishment of the Spherical MPZ	295
25.34.3	Temperature Distributions in and about the Zone	297
25.34.4	Reduced-Parameter Formulations of the MPZ Equations	298

25.34.5	Reduced Current-Density Formulations of the MPZ Equations	300
25.34.6	The Introduction of Anisotropic Conduction: The Non-spherical MPZ	302
25.35	Generalization of the MPZ Concept—The Introduction of Cryocooling	303
25.36	Unified Description of Cryostability	306
25.36.1	Description of the Cryostability Maps	306
25.36.2	Summarizing Description	308
25.37	The Dynamics of Quench and Recovery	308
25.37.1	Minimum Propagating Current	308
25.37.2	The Propagation Velocity of Normal Zones	309
25.37.3	Propagation Velocity and Stability	310
25.38	Measurement of Normal-Zone Propagation Velocity—Case Studies of Conductor and Coil Stability	312
25.39	Transient Stabilization	314
25.39.1	The Compromise Between Stability and Conductor or System Performance	314
25.39.2	The Critical-Current-Margin Criterion	316
	(a) Heat Transfer Considerations	316
	(b) Operating Current Considerations	317
25.40	Components of the CCM Criterion	317
25.40.1	Elements of the Theory	317
25.40.2	Heat Transfer to Liquid He	318
	(a) Introduction to Heat Transfer	318
	(b) Transient Heat Transfer	318
	(c) Transient Recovery Behavior	319
25.40.3	Disturbance Density	319
25.40.4	Kapitza Conductance at the Conductor/Bath Interface	320
	PART 3. CONCLUDING REMARKS	372
25.41	Adiabatic Stabilization	320
25.42	Chapter Summary	321
25.42.1	The Heat Balance Equation	321
25.42.2	Definition of Terms	323
	Chapter 26. AC Loss	
26.1	Introduction	325
26.1.1	Hysteretic and Eddy-Current Losses in Composite Conductors	325

(a)	Separation of the Losses in Simple Theory . . .	325
(b)	Formats and Functional Forms	326
(c)	Frequency Ranges for the Classification of AC Loss	326
26.1.2	Organization of the Chapter	327
26.2	Hysteretic AC Loss in Isolated Filaments	328
26.3	Influence of Circulating Currents on the External-Field-Induced AC Loss	331
26.3.1	Magnetization of a Twisted Filamentary Composite—Elementary Theory	332
26.3.2	Enhancement of AC Loss by Filament/Applied-Field Coupling	334
(a)	Twist Pitch and Ramp Rate	334
(b)	Transverse or Effective Matrix Resistivity	336
(c)	Coupling Loss in <i>In Situ</i> Processed Superconductors	337
26.3.3	Critical Frequencies and Relaxation Times	338
(a)	The “Current-Transfer” Approach	338
(b)	The Electromagnetic Relaxation Time	338
(c)	Critical Skin Depth Approach	339
26.4	Self-Field-Induced Hysteretic Loss	340
26.5	Development of the Theory of AC Loss in Monoliths, Cables, and Braids	342
26.6	Eddy-Current Loss	343
26.6.1	Eddy-Current Loss at Low Frequencies	343
26.6.2	Eddy-Current Loss in the Low-to-Intermediate-Frequency Regime	345
26.6.3	Separation of Eddy-Current and Hysteretic Losses	347
26.7	The Anisotropic Continuum Model for AC Loss	348
26.7.1	The Characteristic Frequencies	348
26.7.2	The Transverse Resistivity	349
26.7.3	Some Typical Results	349
26.7.4	AC Loss over the Entire Audio-Frequency Spectrum	350
26.8	Total AC Loss as a Function of Amplitude, H_m , and Frequency, f , of a Transverse Applied Field	351
26.8.1	Low-Frequency Region	353
26.8.2	Intermediate-Frequency Region	354
26.8.3	Skin-Effect Region, $f \gg f_{c2}$	355
26.8.4	Summary	356
26.9	AC Loss in a Longitudinal Applied Field	356
26.10	AC Loss in a Current-Carrying Conductor	358
26.10.1	Alternating Transport Current in Zero Applied Field	358

26.10.2	Direct Transport Current in an Alternating Applied Field	361
26.10.3	Alternating Transport Current in the Presence of an Alternating Applied Field	361

Chapter 27. Conductor Design

27.1	Filamentary Conductors	369
27.1.1	Electrical and Geometrical Motivation for Filamentary Subdivision	369
27.1.2	Filamentary Subdivision as a Requirement for Stability	369
27.1.3	Filamentary Subdivision in the Minimization of AC Loss	370
27.1.4	Summary—Five Reasons for Filamentary Subdivision	371
	(a) The Cold Work Requirement	371
	(b) Adiabatic Flux-Jump Stability	371
	(c) Dynamic Flux-Jump Stability	371
	(d) “Cryogenic Stability”	371
	(e) Residual Magnetization and Hysteresis Loss	372
27.1.5	Conclusion	372

PART 1. CONDUCTOR DESIGN—STABILITY CONSIDERATIONS

27.2	Stability Considerations in Conductor Design	372
27.2.1	Properties of the Adiabatic Stability Equation	373
27.3	Filament Diameter	374
27.3.1	Adiabatically Stable Filament Diameter	374
27.3.2	Dynamically Stable Filament Diameter	375
27.3.3	Cryostable Filament Diameter	375
27.3.4	Numerical Examples	375
27.4	Twist Pitch	376
27.4.1	Coupling of the Filaments to an External Field	376
27.4.2	Twist-Pitch Selection for Low $\dot{H}_a$	377
27.4.3	Twist Pitch Selection for High $\dot{H}_a$	377
27.5	Limitations on Strand Diameter and Number of Filaments	378
27.5.1	Strand Diameter under Twist-Pitch Limitation	378
27.5.2	Strand Diameter under Adiabatic Self-Field Limitation	379
27.5.3	Strand Diameter under Dynamic Self-Field Limitation	380
27.5.4	Strand Diameter in Full Critical-Current Cryostability	382

27.6	Cryostabilities of Some Large Conductors	383
27.6.1	The MFTF Conductor	385
27.6.2	The LCT Conductors	385
	(a) The 8-T LCT Conductor	386
	(b) The 5-T LCT Conductor	386
	(c) Improved-Performance LCT Conductors	387
27.7	General Requirements for Stable Conductor Design	387
27.7.1	Flux-Jump Stability	387
27.7.2	Cryostability	388
27.7.3	Surface Cooling in Full Cryostability	388
	(a) Steady State Cooling	388
	(b) Transient Cooling	390

PART 2. CONDUCTOR DESIGN—AC-LOSS CONSIDERATIONS

27.8	AC-Loss Considerations in Conductor Design	390
27.8.1	Significance of the Lower Characteristic Frequency, f_{c1}	391
27.9	Design Requirements for Low AC Losses	392
27.10	Filament Diameter, w	392
27.11	Conductor (Strand) Diameter, D	393
	27.11.1 Eddy-Current Loss	393
	27.11.2 Self-Field Loss	393
27.12	Twist Pitch, L_p	394
27.13	Matrix Resistivity, ρ_L	395
	27.13.1 Matrix Resistivity and Stability	395
	27.13.2 Matrix Resistivity and Conductor Fabricability	395
	27.13.3 Estimation of the Required Matrix Resistivities	395
	27.13.4 Location of the Eddy-Current Barriers	396
27.14	Monolithic Conductors for Pulsed-Field-Applications	397
	27.14.1 Mixed-Matrix Composites—Component Arrangement	397
	27.14.2 Further Control of the Eddy Currents	399
	27.14.3 Calculation of the Matrix Resistivity	399
	27.14.4 Fine Adjustment of the Matrix Resistivity	401

PART 3. THE DESIGN OF STRANDED CONDUCTORS—STABILITY AND AC LOSS

27.15	Design Philosophy	402
27.16	Properties of the Typical Basic Strand	404
	27.16.1 Stability	404
	(a) Dynamic Stability (see Section 27.3.2)	404

(b)	Dynamic Self-Field Stability at $i = 0.75$ (see Section 27.5.3)	404
(c)	Cryostability (see Section 27.6)	405
27.16.2	AC Losses	405
(a)	Hysteretic Loss	405
(b)	Self-Field Hysteretic Loss	405
(c)	Eddy-Current Loss	405
27.16.3	Stability and Loss Status of the Basic Strand—General Assessment	405
27.17	Strand Loss in a Model 1.5-MJ Pulsed Coil	406
27.18	Special Strand and Subcable Designs	406
27.19	Cable Designs for High-Current AC or Pulse Applications	407
27.19.1	Dynamically Stabilized Cable	407
27.19.2	Cryostabilized Cables	408
(a)	Cables with Limited Cryostability	408
(b)	Fully Cryostable Cables	410
27.20	Braid Designs for High-Current Pulse or AC Applications	413
27.20.1	Flat Braid	414
27.20.2	Lattice Braid	416
27.21	Cables and Braids for Precision-Field Applications	418

Chapter 28. Conductor Fabrication

PART 1. FABRICATION OF MONOLITHS AND STRANDS

28.1	Superconductor Materials	421
28.1.1	Niobium and Tantalum	421
28.1.2	Titanium	422
28.1.3	Ti–Nb Alloy Rod	422
28.2	Stabilizer Materials	424
28.2.1	Electrical Resistivity of Copper and Its Magnetic Field Dependence	424
28.2.2	Magnetoresistance of Aluminum	427
28.2.3	Electrical Resistivities of Aluminum and Copper	429
28.2.4	Thermal Conductivities and Magnetothermal Conduc- tivities of Aluminum and Copper	430
28.2.5	Calorimetric Properties of Aluminum and Copper	432
28.2.6	Summary of the Relative Properties of Aluminum and Copper Stabilizers	433
(a)	Electrical Conductivity	433

(b)	Thermal Conductivity	433
(c)	Specific Heat	433
(d)	Enthalpy	433
(e)	Radiation Transparency	433
(f)	Annealing Properties	433
(g)	Surface Treatment	433
(h)	Density	433
(i)	Other Properties	433
28.3	Billet Design	434
28.3.1	Eddy-Current Barriers	434
(a)	Fabricated Barriers	434
(b)	Plated Barriers	434
(c)	Bulk Matrix Resistivity Adjustment	435
28.3.2	Billet Packing Geometries—Hexagonal Elements without Filler Pieces	435
(a)	The Systematic Removal Scheme	435
(b)	Numerical Examples	438
(i)	Variation of Z at Constant n	438
(ii)	Variation of n at Constant Z	438
28.3.3	Summary—Influence of n and Z on the Filling Factor, F_f	438
28.4	Billet Assembly	440
28.4.1	Fabrication of the Elements	440
28.4.2	Billet Packing	441
28.4.3	Cleanliness during Assembly	442
28.4.4	Billet Consolidation	443
28.4.5	Billet Closure	444
28.5	Metalworking	445
28.5.1	The Processing Sequence	445
28.5.2	Early and Unconventional Methods of Conductor Fabri- cation	445
28.5.3	Extrusion Presses	447
28.5.4	Stem Force and Extrusion Pressure	450
28.5.5	Stem Speed	452
28.5.6	Billet Temperature	454
(a)	Pre-Extrusion Temperature	454
(b)	Billet-Preheating Methods	455
(c)	Billet Temperature during Extrusion	455
28.5.7	Interdiffusion Between Elements	455
(a)	Interdiffusion Between Ti-Nb and Cu during Billet Preheating and Extrusion	455
(b)	Interdiffusion Between Cu-Ni and Cu	457
28.5.8	Final-Stage Metalworking Processes	457

(a)	Rod and Wire Drawing	457
(i)	Rod Drawing	457
(ii)	Wire Drawing	457
(b)	Thermomechanical Processing Schedules	459
(c)	Influence of Cold Deformation on the Mechanical and Electrical Properties of the Conductor	459
(d)	Final-Size Heat Treatment	460
28.6	Aluminum Stabilized Conductors	460
28.6.1	Strength and Reinforcement of the Aluminum-Stabilized Conductor	461
28.6.2	Radiation Effects	461
28.6.3	Commercial Aluminum Alloys as Eddy-Current Barriers	462
28.6.4	Summary of the Cryophysical-Property, Mechanical-Property, and Economic Advantages and Disadvantages of Aluminum as a Stabilizer	462
28.6.5	Fabrication of Al-Stabilized Composites	463
(a)	Single-Stage Processing of Al/Ti-Nb Composites	463
(b)	Two-Stage Processing of Al/Ti-Nb Composites	465
(c)	Hybrid Aluminum-Stabilized Cu/Ti-Nb Composites	465
28.7	Strands and Monolithic Conductors—Further Selected Examples	467

PART 2. FABRICATION OF CABLE AND BRAID

28.8	The Fabrication of Cable	471
28.9	Geometry of the Cabling Process	471
28.10	Geometry of a Flat Cable	473
28.10.1	Filling Factor and Aspect Ratio	473
28.10.2	Transposition Status of Flattened Monoliths and Flat Cables	475
28.11	Impregnation of Cables	475
28.12	Hybrid “Monolithic Cables”	476
28.12.1	Imbedded Cables	476
28.12.2	The Compacted Cable and the Compacted Monolith	477
(a)	The Compacted Cable	477
(b)	The Compacted Monolith	478
(c)	Advantages and Disadvantages	479
28.13	Cabled Conductors—Further Selected Examples	479
28.14	The Fabrication of Braid	480
28.14.1	Rotary Braiding	481

28.14.2	Maypole Braiding	482
(a)	General Principles	482
(b)	Round and Flat Braid	483
(c)	Lattice Braid	485

PART 3. FABRICATION OF TERMINATIONS AND JOINTS IN Cu/Ti-Nb COMPOSITE SUPERCONDUCTORS

28.15	Conductor Termination and Current Transfer	486
28.16	Fabrication of Joints	487
28.16.1	Spot Welding	487
28.16.2	Ultrasonic Welding	489
28.16.3	Resistance Welding	489
28.16.4	Soldered Lap Joints	490
28.16.5	Pressure Contact	491
28.16.6	Explosive Bonding	492
28.16.7	Cold-Pressure Welding	493

VII: PROPERTIES OF COMPOSITE SUPERCONDUCTORS

Chapter 29. Stress Effects

29.1	Effects of Stress on Materials and Systems Properties	497
29.1.1	Mechanical Properties	497
29.1.2	Fundamental Superconducting Properties	498
(a)	Superconducting Transition Temperature, T_c	498
(b)	Upper Critical Field, H_{c2}	498
29.1.3	Training and Electrical Fatigue	499
(a)	Training	499
(b)	Electrical Fatigue	499
29.2	Training	500
29.2.1	General Observations	500
29.2.2	The Structure—Macroscopic Thermomechanical Effects	501
29.2.3	The Structure—Microscopic Thermomechanical Effects	501
29.2.4	The Conductor—Bauschinger Effect in the Copper Stabilizer	502
29.2.5	The Conductor—Plastic Instability in the Ti-Nb Superconductor	505
29.2.6	Prestrain	506
29.2.7	Origins and Permanence of Coil Training	507

29.3	Deterioration of Current-Carrying Capacity	508
29.4	Static Stress Effects	512
29.4.1	Experimental Details	512
29.4.2	Mechanisms of Static Critical-Current Deterioration . .	514
29.4.3	General Discussion of the Static Strain Effect	515
29.4.4	Systematics of the Static Strain Effect	516
	(a) The $J_c-H_{c2}-(T_c)-\epsilon_c$ Critical Surface	516
	(b) The Strain Window	517
29.5	Dynamic Stress Effects	519
29.6	Dynamic Stress Effects—Repeated Tension	520
29.6.1	Electrical Deterioration of the Superconductor	520
29.6.2	Electrical Deterioration of the Matrix	520
29.7	Dynamic Stress Effects—Tension–Compression	520
29.7.1	Electrical Deterioration of the Matrix	520
29.7.2	Electrical Deterioration of the Superconductor	522

Chapter 30. Radiation Effects

30.1	High-Energy Radiation Damage	528
30.1.1	Electron Damage	529
30.1.2	Proton Damage	529
30.1.3	Neutron Damage	530
30.1.4	Gamma-Radiation Damage	530
30.2	The Particle-Accelerator Environment	530
30.3	Electron Irradiation of Ti–Nb Superconductor	533
30.4	Proton Irradiation of Ti–Nb Superconductor and Its Stabilizer	533
30.4.1	Changes in Critical Current Density	533
30.4.2	Resistivity of the Copper Matrix	536
30.5	Deuteron Irradiation of Ti–Nb Superconductor	537
30.5.1	Helium-Temperature Irradiation	537
30.5.2	Room-Temperature Irradiation	537
30.6	The Fusion Reactor Environment in general	538
30.7	The Tokamak Reactor Environment	540
30.7.1	Magnetic Requirements and General Description . . .	540
30.7.2	Radiative Output of the Tokamak Plasma	541
30.7.3	Selection of the Inner Blanket/Shield Thickness, Δ_{BS}^i .	541
30.7.4	Simulation of the Fusion Reactor Environment	543
30.8	Neutron Irradiation of Cu/Ti–Nb Composite Superconductors	550
30.8.1	Introduction	550
30.8.2	Experimental Conditions	550
	(a) Neutron Energy	550

(b) Neutron Fluence 551

(c) Sample Temperature during Irradiation 552

30.8.3 Critical Temperature and Critical Field of Irradiated Ti-Nb 552

30.9 Critical Current Density of Neutron-Irradiated Ti-Nb . . 552

30.9.1 Low-Temperature Irradiation 552

30.9.2 Ambient-Temperature Irradiation 554

30.9.3 Flux-Pinning Mechanisms under Neutron Irradiation . 556

30.9.4 Low-Temperature Irradiation and Cycling to Room Temperature 556

30.10 Radiation Damage to Stabilizer and Insulating Materials 558

30.10.1 Neutron Damage and Recovery in Al and Cu 558

30.10.2 Neutron-Induced Deterioration of Conductor Stability 559

30.10.3 Neutron Irradiation of Cu with Cycling to Room Temperature 560

30.10.4 Gamma-Irradiation of Organic Insulating Materials . 563

References 567

Definition of Symbols and Abbreviations 607

Index of Plotted and Tabulated Data (Cumulative for Volume 1 and Volume 2) 625

Subject Index (Cumulative for Volume 1 and Volume 2) 633